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DECLARATION FOR PATENT APPLICATION (WITH POWER OF ATTORNEY)

As an inventor named below or on any attached continuation page, I hereby declare that:

My residence, post office address and citizenship are as stated next to my name.

I believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled METHOD FOR ENCAPSULATING INTERMEDIATE CONDUCTIVE ELEMENTS CONNECTING A SEMICONDUCTOR DIE TO A SUBSTRATE AND SEMICONDUCTOR DEVICES SO PACKAGED, the specification of which (check one):

- is attached hereto.
- was filed on July 26, 2001 as United States application serial no. 09/916,197.
- was filed on _____ as PCT international application no. _____ and was amended under PCT Article 19 on _____.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose to the U.S. Patent and Trademark Office all information known to me to be material to the patentability of the subject matter claimed in this application, as "materiality" is defined in Title 37, Code of Federal Regulations § 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, § 119(a)-(d) or § 365(b) of any foreign application(s) for patent or inventor's certificate or § 365(a) of any PCT international application(s) designating at least one country other than the United States of America listed below and on any attached continuation page and have also identified below and on any attached continuation page any foreign application for patent or inventor's certificate or any PCT international application(s) designating at least one country other than the United States of America having a filing date before that of the application(s) on which priority is claimed.

Prior foreign/PCT application(s):

200103014-7 (number)	Singapore (country)	21/05/2001 (day/month/year filed)	Priority Claimed	
			X Yes	No
(number)	(country)	(day/month/year filed)	Yes	No

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) or § 365(c) of PCT international application(s) designating the United States of America listed below and on any attached continuation page and, insofar as the subject matter of each of the claims of this application is not disclosed in any such prior application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose to the U.S. Patent and Trademark Office all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations § 1.56 which became available between the filing date of such prior application and the national or PCT international filing date of this application:

_____ (application serial no.)	_____ (filing date)	_____ (status - pending, patented or abandoned)
_____ (application serial no.)	_____ (filing date)	_____ (status - pending, patented or abandoned)

I hereby claim the benefit under Title 35, United States Code, § 119(e) of any United States provisional application(s) listed below:

_____ (provisional application no.)	_____ (filing date)
-------------------------------------	---------------------

I hereby appoint the following Registered Practitioners to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

David V. Trask, Reg. No. 22,012
 Joseph A. Walkowski, Reg. No. 28,765
 Allen C. Turner, Reg. No. 33,041
 Brick G. Power, Reg. No. 38,581
 Krista Weber Powell, Reg. No. 47,867
 Shawn G. Hansen, Reg. No. 42,627
 Katherine A. Hamer, Reg. No. 47,628

William S. Britt, Reg. No. 20,969
 James R. Duzan, Reg. No. 28,393
 Edgar R. Cutaxinos, Reg. No. 39,931
 Paul C. Oestreich, Reg. No. 44,983
 Jarrett K. Abramson, Reg. No. 47,376
 Bretton L. Crockett, Reg. No. 44,632
 Michael L. Lynch, Reg. No. 30,871

Laurence B. Bond, Reg. No. 30,549
 H. Dickson Burton, Reg. No. P-48,396
 Kent S. Birmingham, Reg. No. 30,453
 Devin R. Jensen, Reg. No. 44,805
 David L. Stott, Reg. No. 43,937
 Bradley B. Jensen, Reg. No. 46,801
 Charles B. Bramley II, Reg. No. 38,086

Address all correspondence to: Brick G. Power, telephone no. (801) 532-1922, TRASKBRITT, PC, P.O. BOX 2550, Salt Lake City, Utah 84110

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or issued thereon.

Full name of first joint inventor: Chong Chin Hui

Inventor's signature _____

Residence: Singapore

Citizenship: Republic of Singapore

Post Office Address: Block 239, Lor 1 Toa Payoh #04-100, Singapore 310239

Date: 12th September 2001

DECLARATION FOR PATENT APPLICATION
(continuation page)

Invention title: METHOD FOR ENCAPSULATING INTERMEDIATE CONDUCTIVE ELEMENTS CONNECTING A SEMICONDUCTOR DIE TO A SUBSTRATE AND SEMICONDUCTOR DEVICES SO PACKAGED

Inventor name(s) appearing on first declaration page: Chong Chin Hui

Additional original, first and joint inventor(s):

Full name of second joint inventor: Lee Kian Chai

Inventor's signature

Residence: Singapore

Citizenship: Republic of Singapore

Post Office Address: Block 235, Compassvale Walk #06-506, Singapore 540235

Lee

Date

09/12/2001

Full name of third joint inventor: Jason Pittam

Inventor's signature

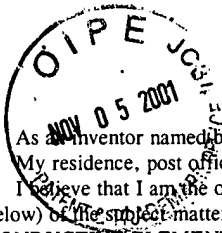
Residence: Morgan Hill, California

Citizenship: U.S.A.

Post Office Address: 16745 Barnell Avenue, Apt. 3, Morgan Hill, California 95037-4922

Date

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My residence, post office address and citizenship are as stated next to my name.

I believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled METHOD FOR ENCAPSULATING INTERMEDIATE CONDUCTIVE ELEMENTS CONNECTING A SEMICONDUCTOR DIE TO A SUBSTRATE AND SEMICONDUCTOR DEVICES SO PACKAGED, the specification of which (check one):

- is attached hereto.
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Prior foreign/PCT application(s):

<u>200103014-7</u> (number)	<u>Singapore</u> (country)	<u>21/05/2001</u> (day/month/year filed)	Priority Claimed <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No
(number)	(country)	(day/month/year filed)	Yes No

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(application serial no.)	(filing date)	(status - pending, patented or abandoned)
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(provisional application no.)	(filing date)

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- | | | |
|---|---|--|
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Kent S. Burningham, Reg. No. 30,453
Devin R. Jensen, Reg. No. 44,805
David L. Stott, Reg. No. 43,937
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Salt Lake City, Utah 84110

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Full name of first joint inventor: Chong Chin Hui
 Inventor's signature _____ Date _____
 Residence: Singapore
 Citizenship: Republic of Singapore
 Post Office Address: Block 239, Lor 1 Toa Payoh #04-100, Singapore 310239

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Inventor name(s) appearing on first declaration page: Chong Chin Hui

Additional original, first and joint inventor(s):

Full name of second joint inventor: Lee Kian Chai

Inventor's signature _____ Date _____

Residence: Singapore

Citizenship: Republic of Singapore

Post Office Address: Block 235, Compassvale Walk #06-506, Singapore 540235

Full name of third joint inventor: Jason Pittam

Inventor's signature  _____ Date 10/30/01

Residence: Morgan Hill, California

Citizenship: U.S.A.

Post Office Address: 16745 Barnell Avenue, Apt. 3, Morgan Hill, California 95037-4922